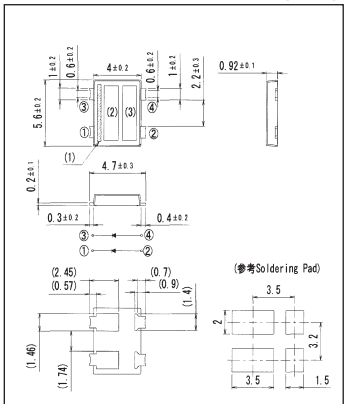
6A Avg. 35 Volts SBD NB06QSA035

■最大定格 Maximum Ratings

Item	Symbol	Conditions			Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	35			V
平均整流電流 Average Rectified Forward Current	I_O	50Hz、正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load ＊1	Ta=25℃＊2 V_{RM}=15V	3.6	A
			Tl=122℃ Tl:lead Temperature V_{RM}=15V	6.0	A
実効順電流 R.M.S. Forward Current	$I_{F(RMS)}$	6.66			A
サージ順電流 Surge Forward Current	I_{FSM}	60	50Hz正弦半波，1サイクル，非くり返し 50Hz Half Sine Wave,1cycle, Non-repetitive		A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	−40～＋150			℃
保存温度範囲 Storage Temperature Range	T_{stg}	−40～＋150			℃

■OUTLINE DRAWING(mm)



■APPROX. NET WEIGHT:0.06 g

■電気的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions		Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	T_j=25℃, V_{RM}=35V, 一素子あたり Per Diode		—	—	2	mA
ピーク順電圧 Peak Forward Voltage	V_{FM}	T_j=25℃, I_{FM}=3A, 一素子あたり Per Diode		—	—	0.47	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	＊2 ガラエポ基板実装	—	—	60	℃/W
	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	—		—	7	℃/W

＊1 カソードコモン動作による/Common Cathode Operation
＊2 ガラエポ基板実装/Glass-Epoxy Substrate mounted (Soldering Lands= 2.0 × 1.5 mm, 2.0 × 3.5 mm , Both Sides)

■定格・特性曲線

FIG.1
順電圧特性
FORWARD CURRENT VS. VOLTAGE

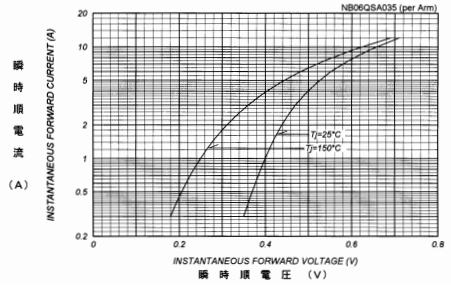


FIG.2
平均順電力損失特性
AVERAGE FORWARD POWER DISSIPATION

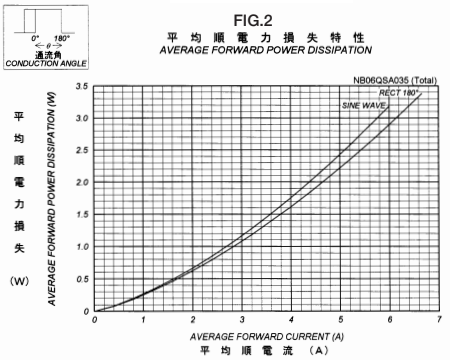


FIG.3
ピーク逆電流 − ピーク逆電圧特性
PEAK REVERSE CURRENT VS. PEAK REVERSE VOLTAGE

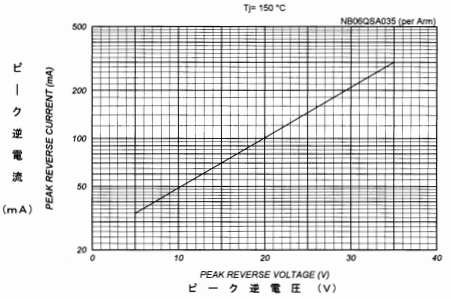


FIG.4
平均逆電力損失
AVERAGE REVERSE POWER DISSIPATION

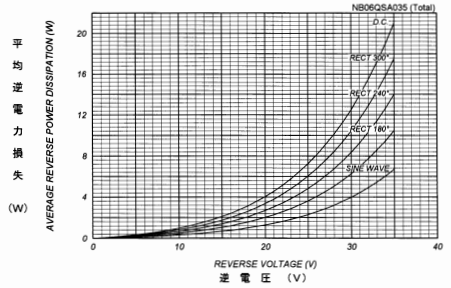


FIG.5
平均順電流 − リード温度定格
AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE

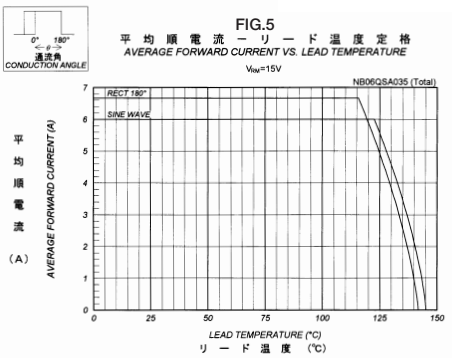


FIG.6
平均順電流 − 周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

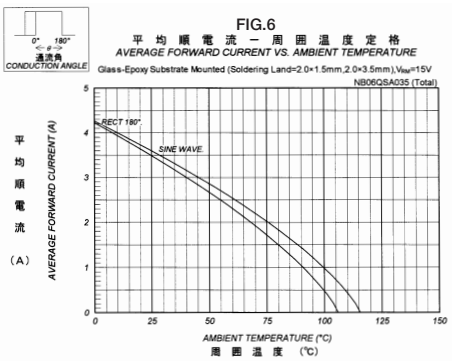


FIG.7
平均順電流 − リード温度定格
AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE

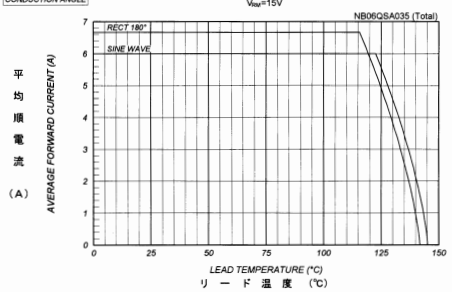
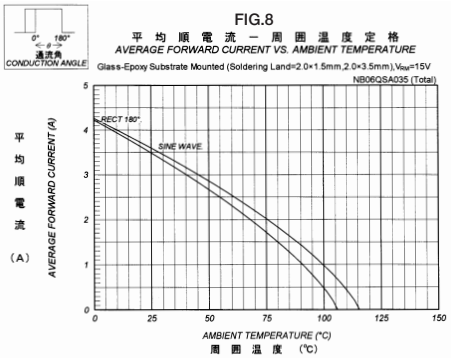



FIG.8
平均順電流 − 周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE